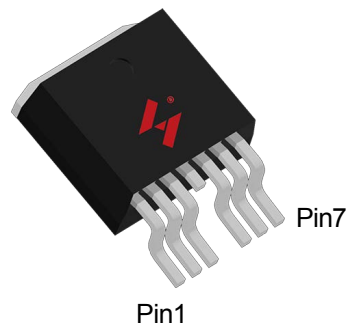


N-Channel Enhancement Mode MOSFET

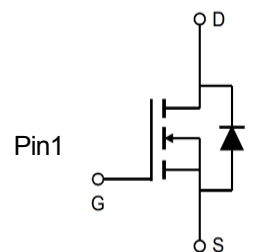
Feature

- 100V/218A
 $R_{DS(ON)} = 3.7m\Omega (typ.) @ V_{GS} = 10V$
- 100% Avalanche Tested
- Reliable and Rugged
- Halogen Free and Green Devices Available
(RoHS Compliant)

Pin Description



TO-263-6L



Pin2,3,5,6,7

N-Channel MOSFET

Applications

- Switch application
- Brushless Motor Drive

Ordering and Marking Information

 B6 HY3810 YYXXXJWW G	Package Code B6:TO-263-6L Date Code YYXXX WW Assembly Material G:Halogen Free
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Note: HUAYI lead-free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature. HUAYI defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (Tc=25℃ Unless Otherwise Noted)				
V _{DSS}	Drain-Source Voltage		100	V
V _{GSS}	Gate-Source Voltage		±25	V
T _J	Maximum Junction Temperature		175	℃
T _{STG}	Storage Temperature Range		-55 to 175	℃
I _S	Source Current-Continuous(Body Diode)	T _C =25℃	218	A
Mounted on Large Heat Sink				
I _{DM}	Pulsed Drain Current *	T _C =25℃	785	A
I _D	Continuous Drain Current	T _C =25℃	218	A
		T _C =100℃	154	A
P _D	Maximum Power Dissipation	T _C =25℃	375	W
		T _C =100℃	187	W
R _{θJC}	Thermal Resistance, Junction-to-Case		0.40	℃/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient **		40	℃/W
E _{AS}	SinglePulsed-Avalanche Energy ***	L=0.5mH	1204	mJ

Note: * Repetitive rating; pulse width limited by max.junction temperature.

** Surface mounted on FR-4 board.

*** Limited by T_{Jmax}, starting T_J=25°C, L=0.5mH, R_G= 25Ω, V_{GS}=10V.

Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY3810			Unit
			Min	Typ.	Max	
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
		T _J =125°C	-	-	50	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	2	3	4	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)*}	Drain-Source On-State Resistance	V _{GS} =10V, I _{DS} =90A	-	3.7	4.4	mΩ
Diode Characteristics						
V _{SD} *	Diode Forward Voltage	I _{SD} =90A, V _{GS} =0V	-	0.8	1.2	V
t _{rr}	Reverse Recovery Time	I _{SD} =90A, dI _{SD} /dt=100A/μs	-	65	-	ns
Q _{rr}	Reverse Recovery Charge		-	103	-	nC

Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HY3810			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	1.5	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =25V, Frequency=1.0MHz	-	7874	-	pF
C _{oss}	Output Capacitance		-	967	-	
C _{rss}	Reverse Transfer Capacitance		-	630	-	
t _d (ON)	Turn-on Delay Time	V _{DD} =50V,R _G =6Ω, I _{DS} =90A,V _{GS} =10V	-	28	-	ns
T _r	Turn-on Rise Time		-	45	-	
t _d (OFF)	Turn-off Delay Time		-	85	-	
T _f	Turn-off Fall Time		-	50	-	
Gate Charge Characteristics						
Q _g	Total Gate Charge	V _{DS} =80V, V _{GS} =10V, I _D =90A	-	208	-	nC
Q _{gs}	Gate-Source Charge		-	35	-	
Q _{gd}	Gate-Drain Charge		-	74	-	

Note: *Pulse test, pulse width ≤ 300us, duty cycle ≤ 2%

Typical Operating Characteristics

Figure 1: Power Dissipation

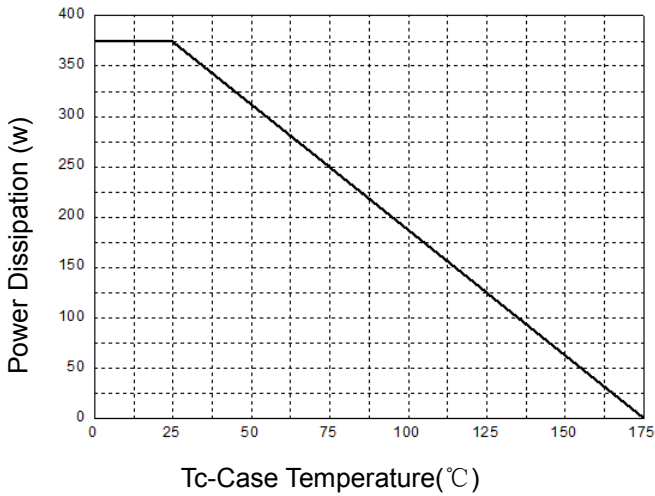


Figure 2: Drain Current

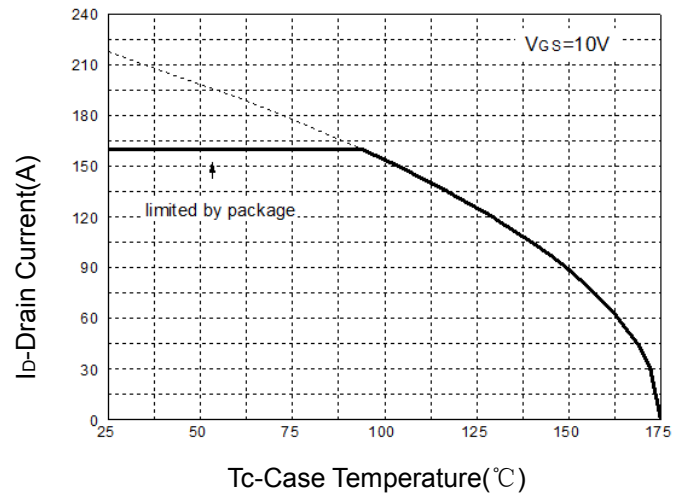


Figure 3: Safe Operation Area

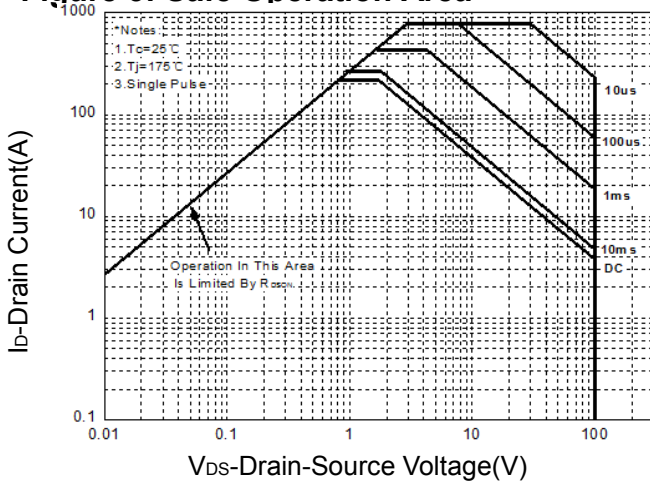


Figure 4: Thermal Transient Impedance

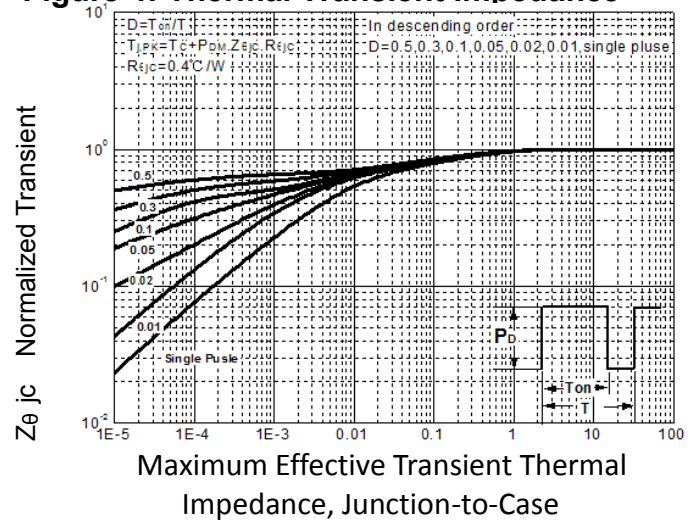


Figure 5: Output Characteristics

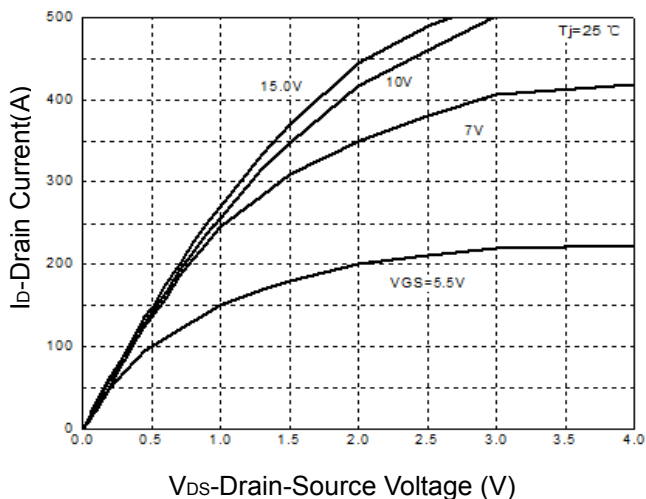
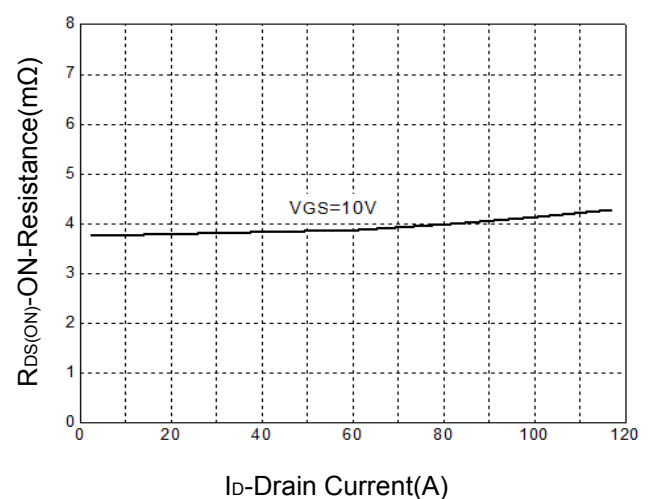


Figure 6: Drain-Source On Resistance



Typical Operating Characteristics(Cont.)

Figure 7: On-Resistance vs. Temperature

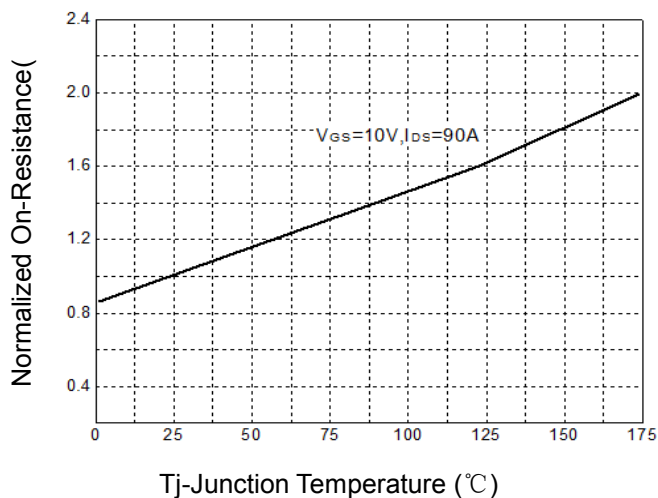


Figure 8: Source-Drain Diode Forward

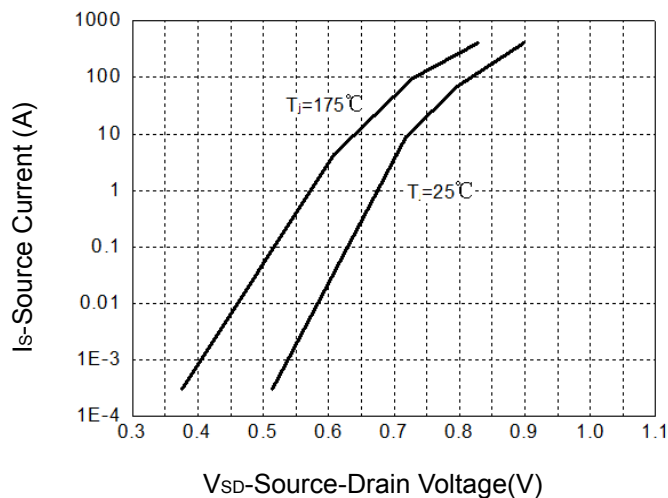


Figure 9: Capacitance Characteristics

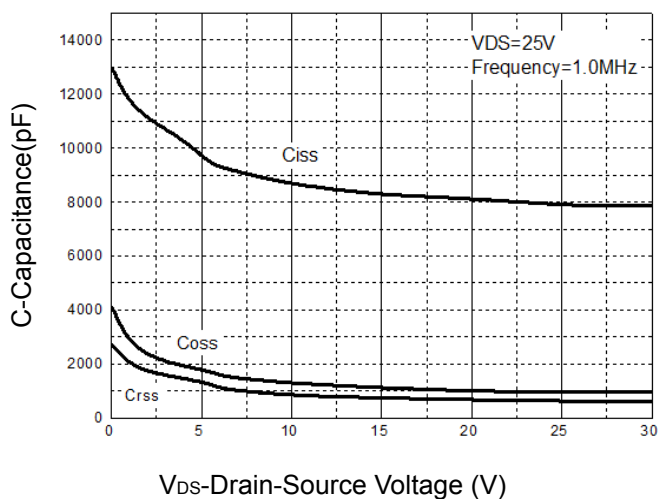
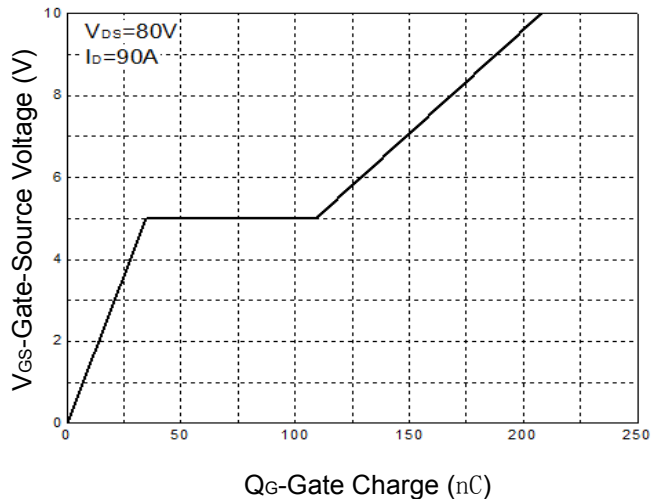
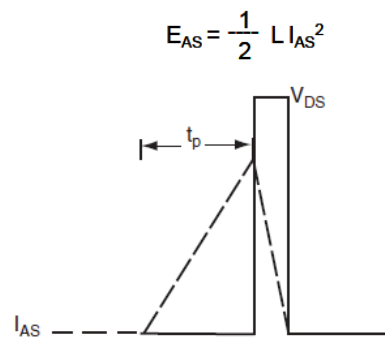
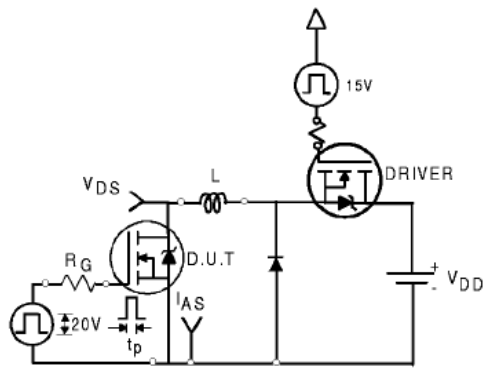


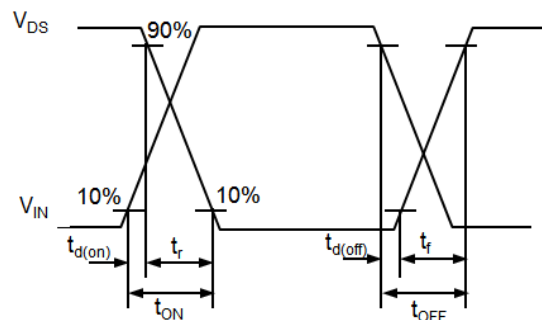
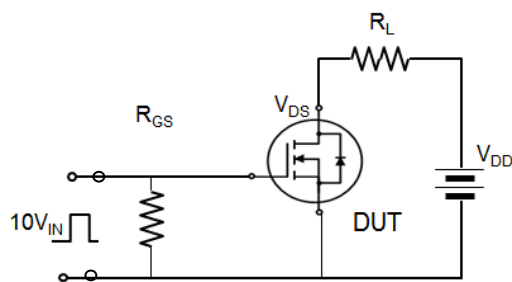
Figure 10: Gate Charge Characteristics



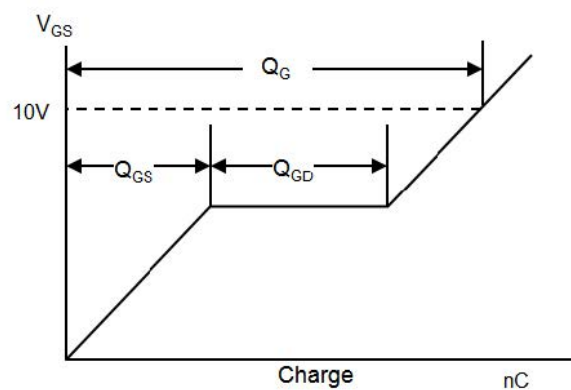
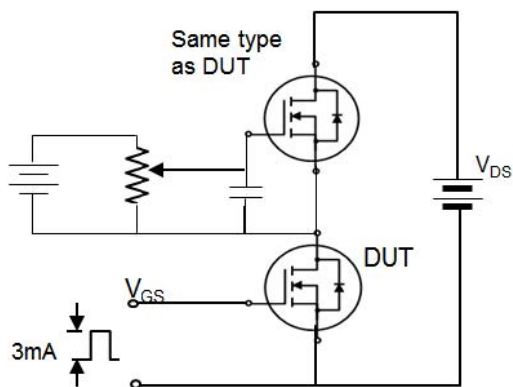
Avalanche Test Circuit



Switching Time Test Circuit



Gate Charge Test Circuit



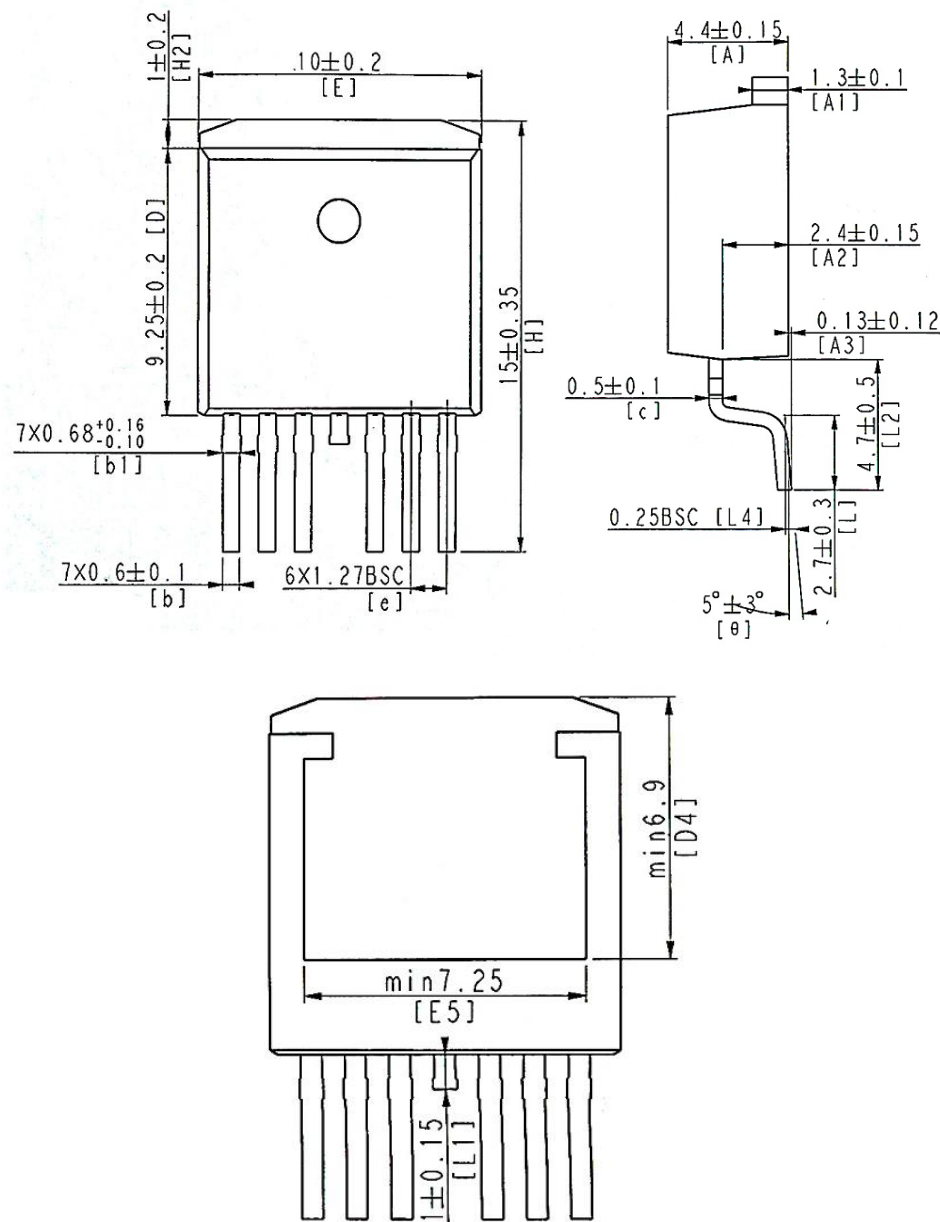
HY3810B6

Device Per Unit

Package Type	Unit	Quantity
TO-263-6L	Tube	50

Package Information

TO-263-6L



The figure illustrates the thermal profile of a solder reflow process. The main graph plots Temperature (°C) against Time (s). Key parameters and regions are labeled:

- T_{smin}**: Minimum solder temperature.
- T_{smax}**: Maximum solder temperature.
- Preheat Area**: The region where the temperature is rising from T_{smin} to T_{smax}.
- t_s**: Time from T_{smin} to T_{smax}.
- t**: Time from the start of the peak to the end of the peak.
- t_p**: Peak time, the duration the temperature is at or above T_c - 5°C.
- Time 25°C to Peak**: The time taken for the temperature to reach the peak from 25°C.

Two inset graphs show the temperature profile at the Supplier and User locations:

- Supplier T_p ≥ T_c**: The peak temperature is at or above the reflow temperature T_c. The dwell time t_p is the duration the temperature is at or above T_c - 5°C.
- User T_p ≤ T_c**: The peak temperature is at or below the reflow temperature T_c. The dwell time t_p is the duration the temperature is at or above T_c - 5°C.

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min ($T_{\min}$)	100 °C	150 °C
Temperature max ($T_{\max}$)	150 °C	200 °C
Time ($T_{\min}$ to $T_{\max}$) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate ($T_{\max}$ to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to $T_{\max}$)	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ ≥2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168 Hrs/500 Hrs/1000Hrs, Bias @ 150°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -55°C~150°C